

DAQ towards a HVCMOS-based tracker for CEPC

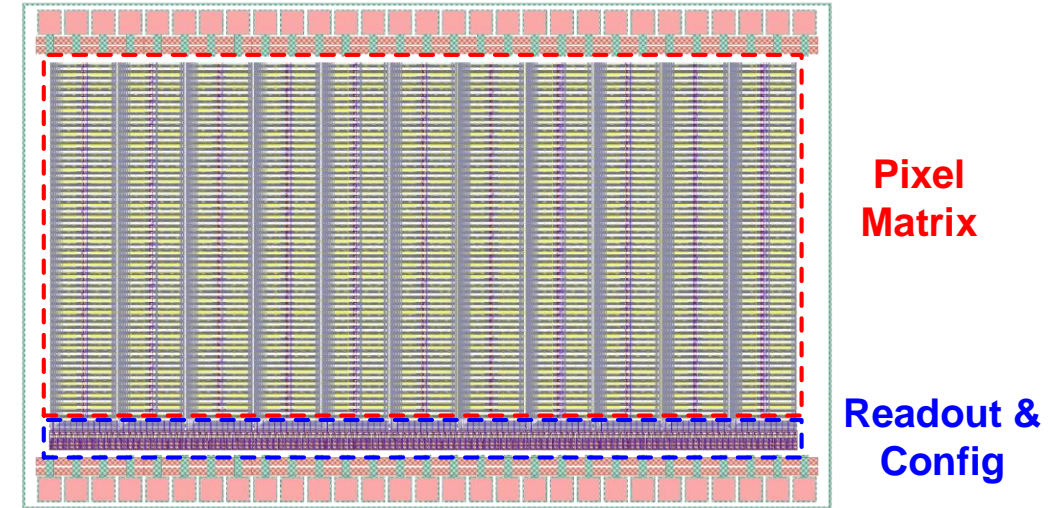
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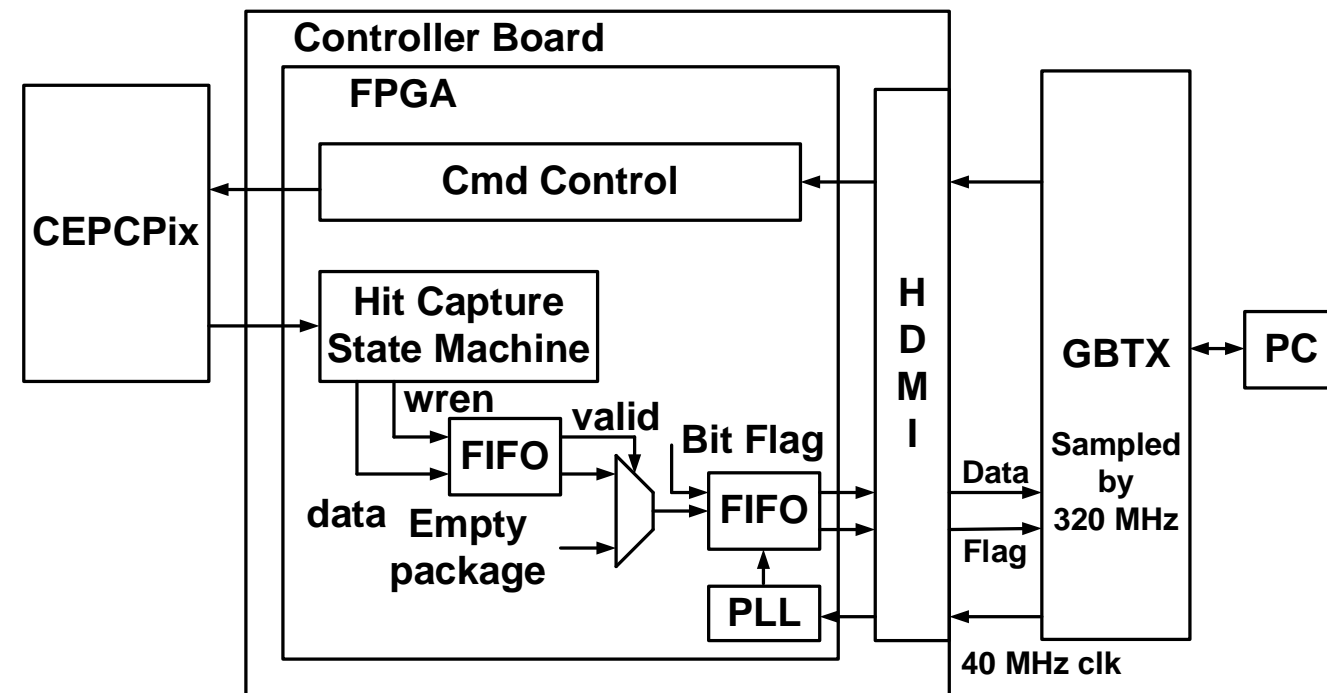
Pixel Sensor for CEPC - CEPCPix

- ▶ Pixel Matrix
 - ◇ Designed in 55 nm technology
 - ◇ 60 rows × 11 columns
 - ◇ Pixel generate a negative pulse when hit
- ▶ Digital Readout Logic
 - ◇ Hit pulse gives out pixel address and hitbus
 - ◇ Hitbus signal starts the serializer for serial output
 - ◇ LVDS output
- ▶ Configuration logic
 - ◇ Shift register
 - ◇ Partner clock and load latch signal for configuration stable



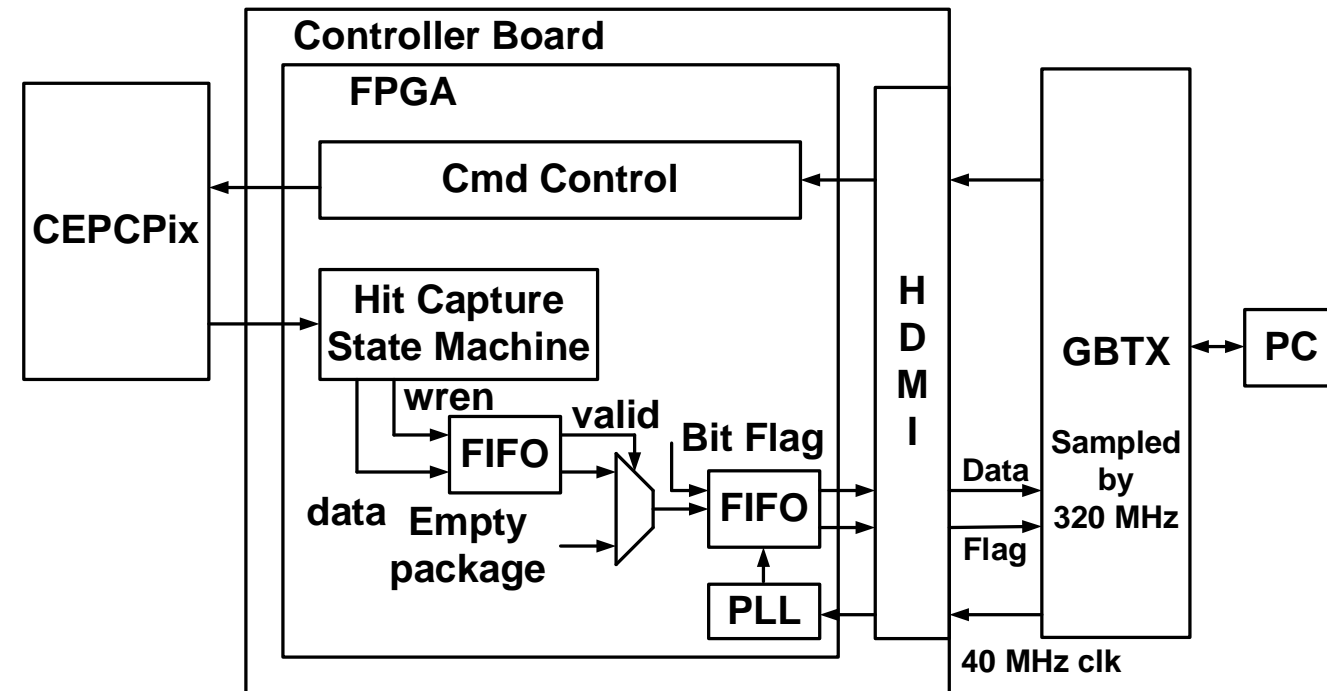
DAQ Design for CEPCPix - Hardware

- ▶ DAQ hardware consist of CEPCPix, Controller board and GBTX
- ▶ Controller Board
 - ◇ Receive data from 4 CEPCPix, could be increased to 8
 - ◇ Hit capture state machine for decoding LVDS data and package
 - ◇ FIFO for crossing time domain from CEPCPix to local
 - ◇ 2 stage FIFO for bit width adjustment
 - ◇ Empty package when no hit data valid



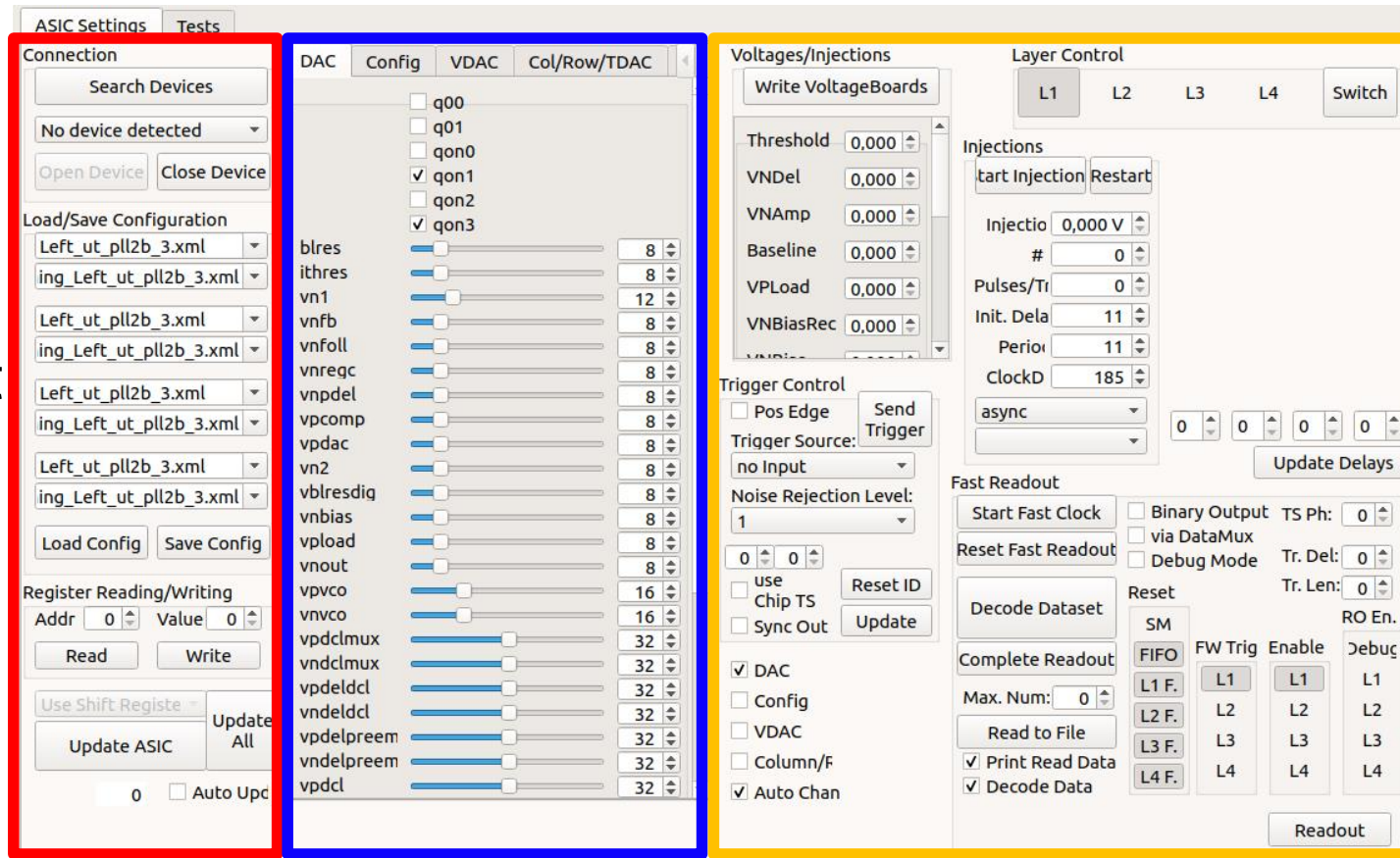
DAQ Design for CEPCPix - Hardware

- ▶ DAQ hardware consist of CEPCPix, Controller board and GBTX
- ▶ GBTX
 - ◇ A radiation tolerant chip for high speed (3.2-4.48 Gbps user bandwidth) bidirectional data transmission
 - ◇ Data, cmd, clk signal within a HDMI link
 - ◇ Receive data and sampled with 320 MHz
 - ◇ GBTX upload data to PC by optical fibers



DAQ Design for CEPCPix - Software

- ▶ QTCreator platform based
- ▶ For 4 pixel sensor control and data receive at present
 - ◇ Connection board for preset configuration parameter import and update config
 - ◇ Setting board for adjusting each parameter, DAC, V_{th} ...
 - ◇ Readout board for setting data receive and decode mode
- ▶ To integrate the interface with GBTX in future



Connection

Setting

Readout